

Local Properties at Interfaces in Nanodielectrics: An *ab initio* Computational Study

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ABSTRACT

First-principles computational methodologies are presented to study the impact of surfaces and interfaces on the dielectric and electronic properties of emerging technologically important systems over length scales of the order of inter-atomic distances. The variation of dielectric constant across Si-SiO₂, Si-HfO₂ and SiO₂-polymer interfaces has been correlated to interfacial chemical bonding environments, using the theory of the local dielectric permittivity. The local electronic structure variation across Si-HfO₂ and SiO₂-polymer interfaces, including band bending, band offsets and the creation of interfacial trap states have been investigated using a layer-decomposed density of states analysis. These computational methods form the groundwork for a more thorough analysis of the impact of surfaces, interfaces, and atomic level defects on dielectric and electronic properties of a wide variety of nano-structured systems.

Index Terms — Dielectric films, dielectric polarization, interface phenomena, density functional theory, electronic structure.

1 INTRODUCTION

IN recent years, dielectric materials of nanoscale dimensions have aroused considerable interest. We mention two examples. First, in the semiconductor industry, in order to keep pace with Moore's law scaling, the thickness of the gate oxide dielectric material is reaching nanoscale dimensions [1, 2]. Second, the high energy density capacitor industry is currently considering dielectric composites with a polymer host matrix filled with inorganic dielectric nanoparticles [3-7] or polarizable organic molecules [8]. The driving force for the former application is high dielectric constants (or high-k), and those for the latter are high-k and/or high dielectric breakdown strengths.

As component sizes or dimensions in multiple-component systems shrink to the atomic or nanoscale, the structure and chemistry at interfaces become important and can sometimes dominate the overall properties. For instance, while atomic level interfacial features such as dangling bonds, under- or over-coordination, multiple-oxidation states, impurities, etc., may be less important in larger scale systems owing to the smaller volume fraction occupied by the interfacial region, the consequences of such effects especially on electrical properties can reach unanticipated magnitudes in nanoscale systems [9-12].

Thus, it is important to characterize the electronic and dielectric properties of interface-containing materials in the nano-regime.

The present investigation constitutes an initial step towards such a fundamental understanding of the relationship between interface structure and chemistry on the one hand, and properties such as interfacial polarization, dielectric response, and electronic structure on the other. Specifically, (i) the extent to which surface/interface effects modify the static and optical *local* dielectric permittivity, and (ii) the evolution of the *local* electronic structure (e.g., the valence and conduction bands) across interfaces as a function of position are addressed using *ab initio* density functional theory based computational methods. Two critical classes of systems are considered in this work. These include interfaces between Si and the inorganic oxides SiO₂ or HfO₂, targeting the first application example mentioned above, and interfaces between model polymers (polyethylene or polyvinylidene difluoride) and SiO₂, relevant for the second application example.

This manuscript is organized as follows. Section 2 discusses the technical details of our computational approach. In Section 3, we describe our theory of the local permittivity, and its application to Si-SiO₂, Si-HfO₂ and SiO₂-polymer interfaces. The local electronic structure across those interfaces is then discussed in Section 4, in terms of the layer-decomposed density of states. We finally conclude with a summary in Section 5.

2 METHODS AND MODELS

Density functional theory (DFT) offers an efficient, accurate and fundamental route to the *ab initio* numerical computation of electronic, atomic, molecular and solid-state properties [13]. Below, we provide details concerning the specific implementation and approximations of DFT as used in the present work.

All calculations were performed using the local density approximation (LDA) within DFT [13] as implemented in the local orbital SIESTA code [14]. Within this implementation, the electronic wave functions are expanded using a double-zeta plus polarization basis set. Electron-ion interactions were represented using norm-conserving non-local pseudopotentials of the Troullier–Martins type, one for each element. The atomic configurations of [Kr4d¹⁰4f¹⁴5s²5p⁶]5d²6s², [Ne]3s²3p², [He]2s²2p⁵, [He]2s²2p⁴, [He]2s²2p², and [H] were used for Hf, Si, F, O, C, and H pseudopotentials, respectively. Semi-core corrections were used for Hf and Si. Integration of properties over the first Brillouin zone was performed via the Monkhorst-Pack *k* point sampling scheme. 75 special *k* points yielded well converged bulk results for Si. The numbers of *k* points used for the bulk SiO₂ in α -quartz and β -cristobalite phases were 108 and 74, respectively, and those for bulk HfO₂ in the cubic and tetragonal phases were 75 and 112. In the case of slab systems containing Si-SiO₂ and Si-HfO₂ interfaces, 64 and 36 special *k* points were required, respectively, to result in well converged results. For the SiO₂-polymer interfaces considered here, namely, polyethylene (PE) on SiO₂ in the α -quartz phase and polyvinylidene difluoride (PVDF) on SiO₂ in the β -cristobalite phase, 18 special *k* points were used. The equilibrium positions of the atoms in all cases were determined by requiring the forces on each atom to be smaller than 0.01 eV/Å.

The computed structural parameters for the model systems described above are listed, and compared with other DFT work and experiments, in Table I. The equilibrium lattice constant of Si in the diamond crystal structure was calculated here to be 5.43 Å, which agrees well with prior DFT calculations [15, 16] and experiments [17]. The equilibrium lattice constants, *a* and *c*, in α -quartz SiO₂ calculated to be 4.91 Å and 5.41 Å, respectively, also agree well with prior DFT calculations [18, 19] and with experimental results [20]. For SiO₂ in the β -cristobalite phase, the calculated lattice constant was 7.49 Å, in reasonable agreement with other theory [21] and experiments [22]. The equilibrium lattice constant of cubic HfO₂ was calculated to be 5.02 Å, and the *a* and *c* equilibrium lattice constants of tetragonal HfO₂ were calculated to be 4.99 Å and 5.06 Å, respectively, all in good agreement with prior DFT calculations [23,24] and experiments [25,26]. A C₁₂H₂₆ hydrocarbon chain and a C₆F₇H₇ chain were used to model PE and PVDF, respectively. As can be seen from Table I, calculated bond lengths in these chains are in good agreement with prior calculations [27, 29, 30] and experiments [28].

Table 1. Comparison of calculated structural parameters of bulk Si, SiO₂, HfO₂, PE, PVDF, and vinylsilanediol with literature values. All distances are in Å.

| System | Lattice constant/ bond length | This work | Other DFT | Expt. |
|--|----------------------------------|-----------|-------------------|-------------------|
| Si | a | 5.43 | 5.48 ^a | 5.43 ^b |
| SiO ₂ (α -quartz) | a | 4.91 | 5.02 ^c | 4.92 ^d |
| | c | 5.41 | 5.53 ^c | 5.41 ^d |
| SiO ₂ (β -cristobalite) | a | 7.49 | 7.14 ^e | 7.17 ^f |
| HfO ₂ (Cubic) | a | 5.02 | 5.04 ^h | 5.08 ⁱ |
| | | | | |
| HfO ₂ (Tetragonal) | a | 4.99 | 5.06 ^h | 5.14 ⁱ |
| | c | 5.06 | 5.12 ^h | 5.25 ⁱ |
| PE | C-C | 1.51 | 1.54 ^j | 1.54 ^k |
| | C-H | 1.12 | 1.10 ^l | 1.10 ^k |
| PVDF | C-H | 1.09 | 1.08 ^l | 1.10 ^k |
| | C-F | 1.36 | 1.37 ^l | 1.34 ^k |
| | C=C | 1.34 | 1.33 ^m | 1.34 ^k |
| Vinylsilanediol | Si-C | 1.83 | 1.87 ^m | 1.89 ^k |
| | Si-H | 1.51 | 1.48 ^m | 1.48 ^k |

^a Reference 15,16; ^b Reference 17; ^c Reference 18,19; ^d reference 20;

^e Reference 21; ^f Reference 22; ^h Reference 23,24; ⁱ Reference 25,26;

^j Reference 27; ^k Reference 28; ^l Reference 29; ^m Reference 30.

3 THE LOCAL PERMITTIVITY

As mentioned in Section 1, owing to the fundamentally different chemistries at surfaces and interfaces compared to the bulk part of a material, the dielectric response is expected to be different in these regions. In fact, our recent work on the scaling with thickness of the dipole moment induced due to an external electric field in ultra-thin SiO₂ [31] and HfO₂ [32] slabs has resulted in the realization that the dielectric properties in the surface regions are considerably different from those of the bulk. This scaling analysis has resulted in an alternative method for the computation of both the static and optical *bulk* polarization and dielectric constant, considerably more efficient than conventional first principles methods [23, 33, 34] used to compute these quantities. Nevertheless, a quantitative estimation of the dielectric constant or polarization at surface and interface regions was not possible using this approach.

Below we present the theory of the *local*, or position-dependent, dielectric permittivity [35, 36], which when combined with DFT computations allows for the determination of such interfacial dielectric response. We then apply this theory to a few important interface containing systems.

3.1 THEORY

The local microscopic dielectric polarization $\vec{p}(\mathbf{r})$ can be obtained from the field induced charge density $\rho_{ind}(\mathbf{r})$ through the in-medium Maxwell equation [37]:

$$\nabla \cdot \vec{p}(\mathbf{r}) = -\rho_{ind}(\mathbf{r}) \quad (1)$$

In the case of multi-layered (1-dimensional) systems with the layers oriented along the *x-y* plane, such as those considered here, Equation (1) reduces to:

$$\frac{d}{dz} \bar{p}(z) = -\bar{\rho}_{ind}(z) \quad (2)$$

where $\bar{p}(z)$ and $\bar{\rho}_{\text{ind}}(z)$ are the polarization and induced charge density along the z -axis, respectively, averaged along the x - y plane. The induced charge density $\bar{\rho}_{\text{ind}}(z)$ can be evaluated as the difference of the total charge densities due to positive ($+\delta$) and negative ($-\delta$) external electric fields along the z direction. In the present work, δ was chosen to be 0.01 V/Å. The solution of Equation (2) is the following:

$$\bar{p}(z) = \bar{p}_{-\infty} - \int_{-\infty}^z \bar{\rho}_{\text{ind}}(z') dz' \quad (3)$$

For the case when our slab system is located about the $z = 0$ plane, the constant $\bar{p}_{-\infty}$ can be set to zero as it corresponds to the polarization at $-\infty$, a region where charge density is zero.

Using the above procedure, both the optical (high frequency) and the static (low frequency) microscopic polarization can be calculated, respectively, by either allowing just the electrons, or both the electrons and the atoms, to respond to the applied external electric field. The local permittivity profile can then be computed from the local polarization using:

$$\varepsilon(z) = \frac{\varepsilon_0 E_{\text{ext}}}{\varepsilon_0 E_{\text{ext}} - \bar{p}(z)} \quad (4)$$

where $E_{\text{ext}} = 2\delta$.

The optical and static local permittivities can be obtained from $\bar{p}(z)$ corresponding to the optical and static cases, respectively [35, 36].

3.2 Si-SiO₂ AND Si-HfO₂ INTERFACES

Miniaturization of electronic devices has already led to ultra-thin (2-3 nm) SiO₂ layers in today's metal-SiO₂-Si gate stacks [9, 38]. In order to keep pace with the miniaturization trend as specified by Moore's law, the SiO₂ dielectric will soon be replaced by a high dielectric constant (high- k) metal oxide [1,2]. The leading contender for the high- k oxide is HfO₂ which has a dielectric constant of about 25, much higher than the SiO₂ dielectric constant of about 4.5. Although Hf-based oxides are thermo-dynamically stable on Si, they are not kinetically stable, and silicides, silicates and SiO_x are known to form at the interface, which have a much lower dielectric constant than HfO₂ [43-46]. An understanding of the factors controlling the dielectric properties of the interface between the dielectric and other materials calls for an accurate determination of atomic-scale dielectric permittivity profiles across layered structures.

The Si-SiO₂ interface has been studied for many decades. We focus on this interface first before moving on to Si-HfO₂. We consider a coherent Si-SiO₂ interface consisting of crystalline Si and SiO₂, of thickness 10.96 Å and 14.70 Å, respectively, with the latter having the β -cristobalite structure.

Figure 1 shows the static and optical permittivity profile across a Si-SiO₂ interface as a function of position along the direction normal to the interface. The dielectric constants in the interior of SiO₂ and Si regions are in excellent agreement with experimental values of the corresponding bulk systems (static and optical values of about 12 for Si [39], and 4.5 and 2.5 for SiO₂ [40, 41], respectively). However, in the transition

region between Si and SiO₂ and close to the outer surface planes, we find an enhancement of the dielectric constant, compared to that of the bulk values. The deviation at the surface is due to the under-coordination of Si atoms, which renders these atoms more polarizable. The enhanced permittivity at the interface (on the SiO₂ side) is due to Si atoms in SiO₂ existing in multiple oxidation states (i.e., Si, Si⁺¹, Si⁺² and Si⁺³) [15, 16], and is in quantitative agreement with capacitance measurements performed on ultra-thin SiO₂ layers on Si [42].

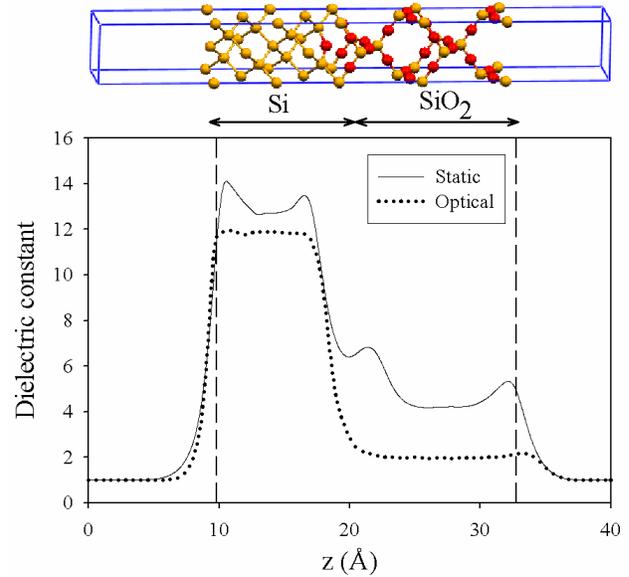


Figure 1. Above: Atomic model of Si-SiO₂ interface, with Si shown in gold, and O in red. In this and all other figures, the atomic model repeats periodically in the plane normal to the interface (x - y) plane. Below: Static (solid) and optical (dotted) dielectric constant of Si-SiO₂ stack as a function of position z normal to the interface.

The Si-HfO₂ interface is poorly understood due to its complicated interfacial structure, especially as new interfacial phases tend to form [43-46]. Here, we consider a simple model of epitaxial Si-HfO₂ primarily to demonstrate the local permittivity approach. Our model was created by placing an O-terminated (001) tetragonal HfO₂ slab on Si such that the HfO₂ slab was coherently matched on top of Si. The thickness of Si and HfO₂ layers were 10.95 Å and 19.91 Å, respectively. The resulting relaxed structure shows that half the interface O atoms move downwards towards Si, and the other half move upwards towards the Hf layer, as shown in Figure 2, thereby forming Si-O-Si and Hf-O-Hf bonds passivating *all* interfacial Si and Hf atoms.

The position-dependent dielectric constant along the Si-HfO₂ interface normal is shown in Figure 2. The dielectric constants in the interior of the HfO₂ and Si regions again match well with the corresponding experimental bulk values (the static and optical permittivities of tetragonal HfO₂ are 16 and 5, respectively [23, 33, 47]). As in the Si-SiO₂ case, enhancement of the permittivities at the free surfaces compared to the corresponding bulk values can be seen here as well, again due to under-coordination of surface atoms. However, in marked contrast with the Si-SiO₂ case, a *decrease* in the permittivity values results in the Si-HfO₂ interface

region relative to the free surfaces. This important behavior even in such an idealized interface is because of the fact that the interface Si and Hf atoms are adequately passivated by the O atoms, resulting in species in their nominal oxidation states (as indicated by a Mulliken charge analysis) and with lower polarizability than the ones at the free surfaces.

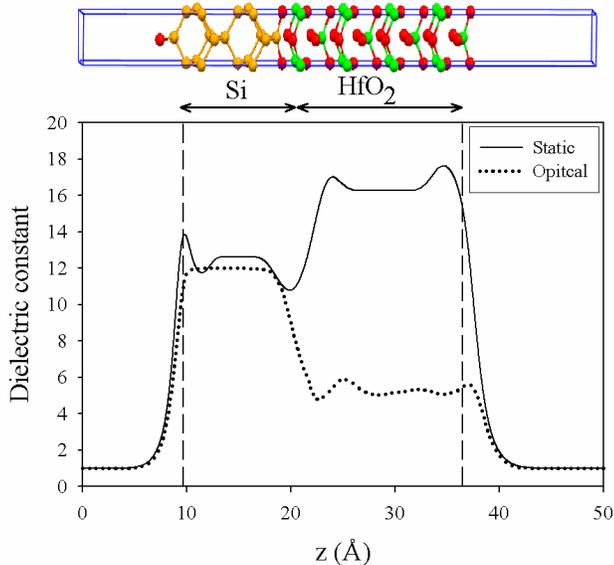


Figure 2. Above: Atomic model of Si-HfO₂ interface with O termination, with Si shown in gold, O in red, and Hf in green. Below: Static (solid) and optical (dotted) dielectric constant of (001) Si-HfO₂ interface as a function of position *z* normal to the interface.

3.3 SiO₂-POLYMER INTERFACE

Polymeric systems constitute an important class of materials for capacitor and insulation technologies [48]. Nevertheless, a quantitative understanding of the electrical response of such systems is still lacking [48, 49]. Polymer-nanocomposites, which have shown promise for electrical applications, form a class of systems that are even less understood. In this section and in Section 4.3, we investigate the dielectric and electronic properties at model polymer-silica interfaces.

Nanocomposites made by blending oxide nanoparticles with polymers are known to display higher effective permittivities than expected from the permittivities of the components, indicating the role played by enhanced interfacial polarization [4-7]. Here, we explore factors that could result in such permittivity enhancements in polymeric systems.

The SiO₂-polymer interface system considered here is composed of SiO₂ in the α -quartz phase of thickness 15.96 Å, and the polymer chain was approximated by a C₁₂H₂₆ molecule. Figure 3 shows the dielectric constant as a function of position along the SiO₂-polymer interface normal. Similar behavior of dielectric constant is observed as with the Si-SiO₂ interface. The agreement is excellent for the dielectric constant in the interior region of SiO₂ and polymer (C₁₂H₂₆) with the corresponding experimental single component bulk values, and the dielectric constant on the SiO₂ side of the interface is enhanced. Analysis of the Mulliken charges of the atoms indicates that C atoms closest to the interface are in

their nominal oxidation states (i.e., in oxidation states similar to that of C atoms in the interior of the polymer chain), whereas the Si and O atoms close to the interface are in varying oxidation states similar to that in the Si-SiO₂ case [20].

Our conclusion of permittivity enhancement at the interface is thus consistent with some prior experimental work [7]. Nevertheless, an *important* point needs to be made. The SiO₂-polymer system modeled here corresponds to a situation in which the SiO₂ surface is “untreated” (which is the experimental situation involving “blends” as in Ref. [7]). However, typical polymeric nanocomposites are made using silane-treated SiO₂ [50-53]. Silane treatment accomplishes the twin purposes of passivation of dangling bonds on silica surfaces by the silane-based initiator molecules, and in the creation of chemical bonds between the initiator and the polymer chains. Thus, silane treatment is expected to *decrease* the polarizability and permittivity at the interface. In fact, recent experimental work indicates that the incorporation of silane-treated SiO₂ nanoparticles into polyethylene results in decreased effective permittivities (although the permittivity of SiO₂ is *higher* than that of the host polymer) [50]. A more comprehensive analysis of SiO₂-polymer interfaces is necessary to understand the circumstances that would result in a permittivity increase or decrease at the interface.

Incidentally, incorporation of silane-treated SiO₂ nanoparticles into polyethylene also resulted in *increased* dielectric breakdown strength [50], while incorporation of micron-sized particles did not. It thus appears that the interface between SiO₂ and polyethylene plays a critical role in controlling the dielectric constant as well as the dielectric strength. These issues are explored further in Section 4.3.

It is worth mentioning that although we have studied only coherent interfaces between dissimilar materials, our approach to computing the local polarization and permittivity can be used to systematically explore a variety of realistic situations, including atomic-level defects (e.g., vacancies), disorder, impurities and initiator species at the interface.

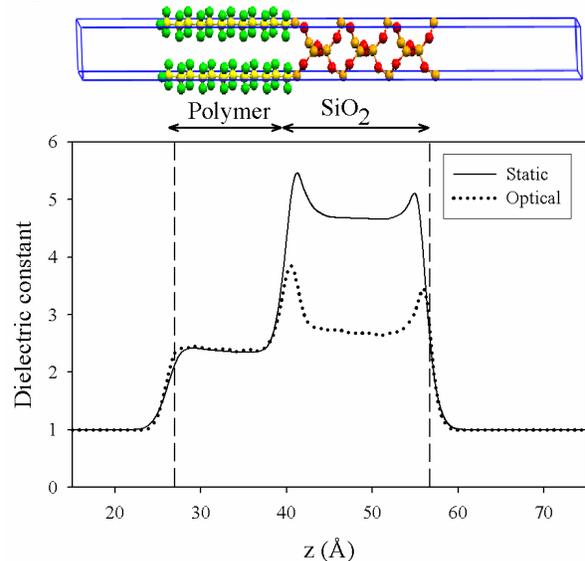


Figure 3. Above: Atomic model of SiO₂-polymer, with Si shown in gold, O in red, C in yellow, and H in green. Below: Static (solid) and optical (dotted) dielectric constant of C₁₂H₂₆-SiO₂ stack as a function of position *z* normal to the interface.

4 THE LOCAL ELECTRONIC STRUCTURE

At the surface of an insulating material or at the interface between two otherwise defect-free insulators, one generally finds under-coordinated atoms. These sub-optimal bonding situations lead to unoccupied and/or occupied states within the band gap of the insulators, which are localized physically at the surface or interface (as opposed to the delocalized bulk Bloch states), and are generally referred to as surface/interface states, defect states, or “trap” states. Reviews of these general notions can be found elsewhere [54, 55]. These defect states are important in two respects. They can alter the polarizability of the surface/interface region, as has been discussed in the previous section, and they can significantly control charge carrier conduction through the insulator. It is the latter possibility that is important in a study of breakdown phenomena.

In the case of *coherent* interfaces between dissimilar insulators, no dangling bonds would exist, and hence, one would not find defect states at the interface. Nevertheless, the energetic positions of the conduction and valence band edges in one material will be offset relative to those of the other material. In addition, the band edges could vary with position resulting in band bending due to transfer of charge from one material to the other at the interface.

It is important to characterize both the band offsets across the interface and the existence of trap states at the interface. Below, we present an approach to study the position dependent variation of the valence and conduction bands across interfaces, and the emergence of trap states at interfaces, using the layer-decomposed density of states (LaDOS) method. We then apply this method to Si-HfO₂ and polymer-SiO₂ interfaces.

4.1 THEORY (LaDOS)

Within the layer-decomposed density of states (LaDOS) approach, the total density of states (DOS) of the entire system is decomposed in terms of its origins from the various atoms of the system on a layer-by-layer basis. Since we are primarily interested in multi-layered systems, the layer decomposition provides the position dependence of the electronic structure that we seek.

Within a local orbital implementation of DFT such as the one adopted here, the electronic wave function $|\Psi_i\rangle$ can be projected onto the atomic orbitals $|\phi_{al}\rangle$ as

$$|\Psi_i\rangle = \sum_{al} \langle \phi_{al} | \Psi_i \rangle |\phi_{al}\rangle \quad (5)$$

where i , a , and l are the indices for the electronic wave function, atom, and the atomic orbital, respectively. The density of states $g_{al}(\epsilon)$, where ϵ is the electronic energy, arising from a specific atom a with atomic orbital l can be defined as:

$$g_{al}(\epsilon) = \sum_i |\langle \phi_{al} | \Psi_i \rangle|^2 \delta(\epsilon - \epsilon_i) \quad (6)$$

where δ represents the Dirac delta function.

The contribution of all the atomic orbitals in one specific atomic layer results in the LaDOS of that layer. As will be demonstrated in the examples below, the LaDOS approach provides significantly more detailed information than the conventional “bulk plus band lineup” method [58, 59] for determining band offsets at interfaces.

4.2 Si-HfO₂ INTERFACE

Since HfO₂ is considered as a promising replacement for SiO₂, a comprehensive investigation of the band profile, band gap variation and band alignment evolution as a function of interfacial bonding with Si is urgently needed [58-61].

Our model of a coherent Si-HfO₂ heterojunction has been described in Section 3.2. The top part of Figure 4 shows the atomic structure of the Si-HfO₂ heterojunction, with dot-dashed rectangular boxes defining each layer. The LaDOS profile corresponding to each layer is displayed in the bottom part of Figure 4, with the valence and conduction bands shown in black and blue, respectively. The LaDOS for layers in the interior region of the Si are essentially same, resulting in a uniform band gap of about 0.45 eV, which compares well with the DFT-LDA band gap of bulk silicon determined by others [62]. Similarly, we obtain a uniform band edge profile in the interior region of HfO₂, and a band gap value of about 4.5 eV, which also compares well with previous DFT-LDA estimates of the HfO₂ band gap [59, 63]. Note that the computed band gaps are underestimated relative to experimental values, consistent with the well known deficiency of DFT-LDA.

Close to the Si-HfO₂ interface, the band edges of one system smoothly evolve to those of the other, resulting in a valence band offset of 3.05 eV between Si and HfO₂. This result compares well with the experimental estimates of 2.94-3.25 eV [59-61] and earlier calculations [58, 59] based on more involved computational treatments. Although LDA tends to underestimate band gaps of insulators relative to experiments, the valence band offsets are generally reproduced accurately. The smooth evolution of the band edges across the interface, and the absence of interfacial defect states is a result of the coherent nature of this interface (which contains no dangling bonds).

A deeper (and more realistic) analysis of this band edge variation dependence on the interfacial bonding and interfacial phases might provide very useful information concerning this important class of systems.

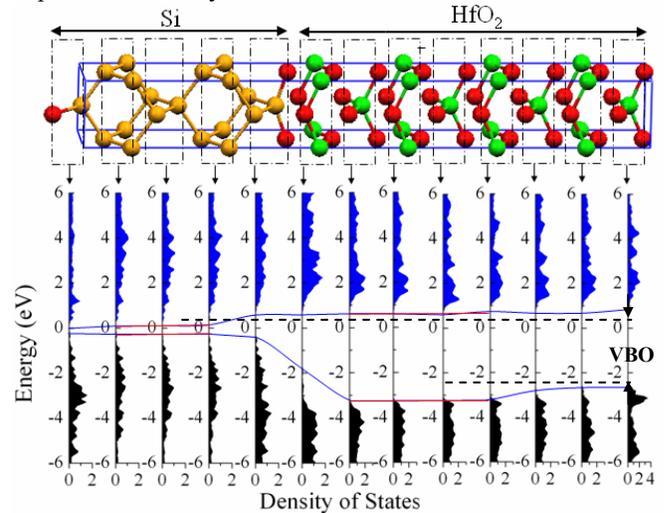


Figure 4. Above: Atomic model of Si-HfO₂ interface with O termination, with Si shown in gold, O in red, and Hf in green. Below: Layer-decomposed Density of States of Si-HfO₂ interface. The conduction band is shown in green, and the valence band in black. The zero of energy is the Fermi energy. The valence band offset (VBO) between Si and HfO₂ is determined to be 3.05 eV.

4.3 SiO₂-POLYMER INTERFACE

As mentioned in Section 3.3, recent experiments involving silane-treated SiO₂ nanoparticles incorporated in polyethylene has shown an increase in dielectric breakdown strength, whereas untreated SiO₂ displays only a modest change in the breakdown strength [50, 51]. It has also been postulated that interface states could act as potential electron traps, thereby scavenging “hot” electrons, and increasing the breakdown strength [56,57]. A systematic investigation of the various types of oxide-polymer interfaces focusing on interface states will help identify trends related to dielectric breakdown strengths, and can aid in the rational design of polymeric systems with superior dielectric properties.

In order to probe the specific role played by the silane treatment of SiO₂, we consider models of SiO₂-polymer interfaces in the presence of a silane-based species at the interface. The chemical route to the incorporation of silane-treated SiO₂ nanoparticles into the polymer involves two separate steps [50]. The SiO₂ nanoparticles are first reacted with silane or its derivatives, resulting in SiO₂ surfaces decorated with the silane-based initiator species. Next, the facile attachment of polymer chains to the initiator species is accomplished. In this work, the initiator is represented by a vinylsilanediol (HSi(OH)₂CHCH₂) molecule, and the polymer chain is C₆H₇F₇, representing polyvinylidene difluoride (PVDF). We find that attachment of the vinylsilanediol initiator to the SiO₂ surface (with a binding energy of -0.58 eV) and the subsequent attachment of C₆H₇F₇ to the initiator (with a binding energy of -0.98 eV) are thermodynamically favored.

The band edge variation with position perpendicular to the SiO₂ surface for a SiO₂-vinylsilanediol-PVDF interface is shown in Figure 5. The LaDOS in the middle parts of the SiO₂ and polymer regions result in a large and uniform band gaps, like in the coherent Si-HfO₂ example discussed above. However, in the interface region that contains the initiator, the band edges do not smoothly evolve from one region to the other. Rather, two peaks, one corresponding to an occupied defect state and another to an unoccupied defect state appear (indicated by circles in Figures 5), whose origins can be traced to the double bond in the vinylsilanediol initiator. Both the unoccupied and occupied states can be classified as “shallow” traps for electrons and holes, respectively, as they are close to the conduction band and valence band edges. These defect states are localized, and could potentially trap itinerant conduction electrons and valence holes, thereby providing opportunities for “cooling” charge carriers.

Although these aspects are consistent with the observed increase in breakdown strength of SiO₂-polymer composites, several questions remain unanswered. Firstly, mechanisms for the dissipation of the energy released during the cooling process need to be addressed. A potential mechanism could be the enhanced interaction between electrons in the polymer and phonons in SiO₂. It is well known that enhanced electron-phonon coupling in SiO₂ is one of the reasons for its high breakdown strength [55-56]. Secondly, the role of the initiator species needs to be clarified, as the trap states appear to be determined largely by the nature of the initiator. Thirdly, a

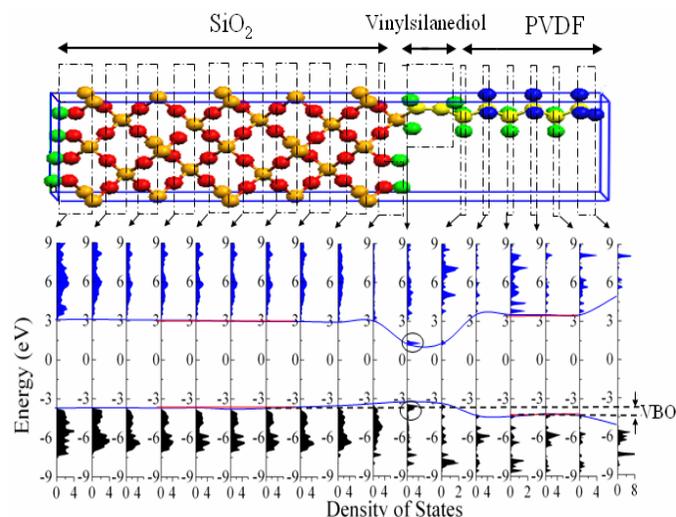


Figure 5. Above: Atomic model of SiO₂-vinylsilanediol-PVDF inter-face, SiO₂ slab with OH termination, with Si shown in gold, C in yellow, O in red, H in green, and F in blue. Below: Layer-decomposed Density of States of SiO₂-vinylsilanediol-PVDF interface. The conduction band is shown in blue, and the valence band in black. The zero of energy is the Fermi energy. Lower and upper circled states represent occupied and unoccupied interfacial defect states, respectively.

variety of SiO₂ and other oxide (e.g., Al₂O₃) surfaces should be studied to understand systematic trends across a wider class of situations. The LaDOS approach provides a practical framework to undertake such systematic studies.

5 SUMMARY

As component sizes or dimensions in multiple-component dielectric materials shrink to the atomic or nanoscale, the structure and chemistry at interfaces become important. Understanding the fundamental relationships between the atomic level interfacial structure and electrical properties such as dielectric response and breakdown is critical. In this work, we have presented two *ab initio* based computational methodologies to probe such structure-property relationships in systems of emerging technological importance.

The theory of the local dielectric permittivity has been developed to understand the variations of the static and optical dielectric constant across idealized Si-SiO₂, Si-HfO₂ and SiO₂-polymer interfaces over length scales of the order of interatomic distances. These variations have been correlated to the chemistry at the interfaces, such as dangling bonds and multiple oxidation states. The layer-decomposed density of states approach has been used to compute the electronic structure variation across Si-HfO₂ and SiO₂-polymer interfaces. This procedure has been used to capture band bending, band offsets and creation of trap states at interfaces. Although further work over a wider range of systems and situations is necessary, the computational tools and their applications described here form the groundwork for a more thorough analysis of the impact of surfaces, interfaces, and atomic level defects on the dielectric and electronic properties of a wide variety of nanostructured systems.

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